

### **100V N-Channel Enhancement Mode MOSFET**

#### Description

The AP8N10MI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 100V I<sub>D</sub> =8A

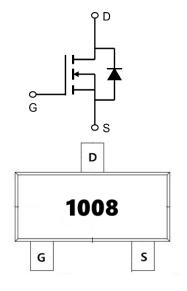
 $R_{DS(ON)} < 100m\Omega@V_{GS}=10V$  (Type: 80mΩ)

#### Application

Automative lighting

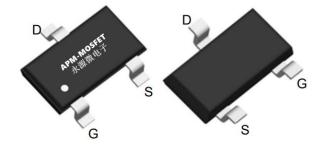
Load switch

PSE



**Top View** 

**Bottom View** 



#### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP8N10MI	SOT23-3L	1008	3000

#### Absolute Maximum Ratings (TC=25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	100	V	
VGS	Gate-Source Voltage	±20	V	
I⊳@Tc=25°C	Drain Current, V <sub>GS</sub> @ 10V	8	А	
I₀@Tc=100°C	Drain Current, V <sub>GS</sub> @ 10V	6.5	А	
IDM	Pulsed Drain Current <sup>1</sup>	24	А	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation	30	W	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	2.7	W	
TSTG	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
RθJA	Maximum Thermal Resistance, Junctionambient 100		°C/W	
RθJC	Maximum Thermal Resistance, Junction-case	rmal Resistance, Junction-case 5.1 °c		

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### Electrical Characteristics@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250µA	100	107	-	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	VDS=0V, VGS=±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250µA	1.2	1.85	2.5	V
		VGS=10V, ID=5A	-	80	100	mΩ
RDS(on)	Static Drain-Source on-Resistance note3	VGS=4.5V, ID=3A	-	95	125	mΩ
g fs	Forward Transconductance	V DS =5V , I D =5A		14		S
RG	Gate Resistance	VDS = 0V, VGS =0V,f =1MHz		3		Ω
Ciss	Input Capacitance		-	1100	-	pF
Coss	Output Capacitance	VDS=15V, VGS=0V, f=1.0MHz	-	55	-	pF
Crss	Reverse Transfer Capacitance			40	-	pF
Qg	Total Gate Charge	VDS=50V,	-	11.9	-	nC
Qgs	Gate-Source Charge	ID=5A,	-	2.8	-	nC
Qgd	Gate-Drain("Miller") Charge	VGS=10V	-	1.7	-	nC
td(on)	Turn-on Delay Time		-	3.8	-	ns
tr	Turn-on Rise Time	VDS=30V, ID=5A,	-	25.8	-	ns
td(off)	Turn-off Delay Time	RG=1.8Ω, VGS=10V	-	16	-	ns
tf	Turn-off Fall Time		-	8.8	-	ns
IS	Continuous Source Current1,5	VG=VD=0V , Force Current	-	-	14.6	А
ISM	Pulsed Source Current2,5		-	-	25	А
VSD	Diode Forward Voltage2	VGS=0V, IS=10A	-	-	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch 2  $\,$  FR-4 board with 2OZ copper.

2 、The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$ 

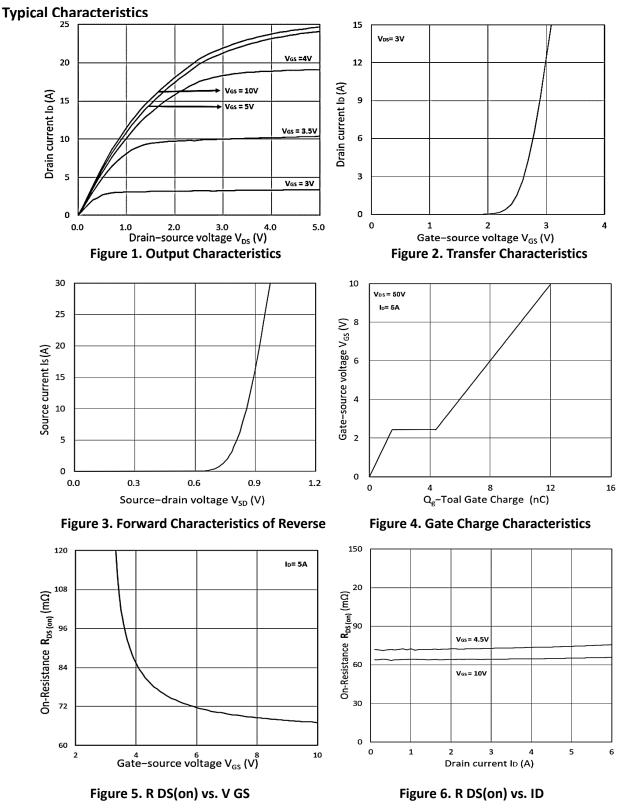
3、The power dissipation is limited by 150°C junction temperature

4、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

N



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## <u>AP8N10MI</u>

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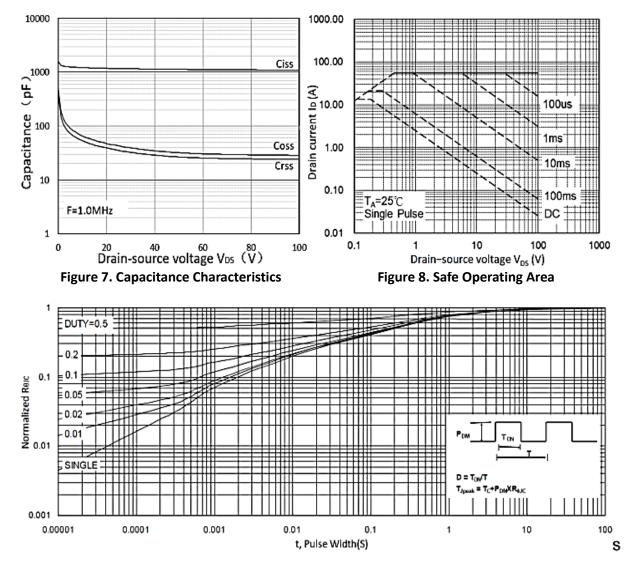
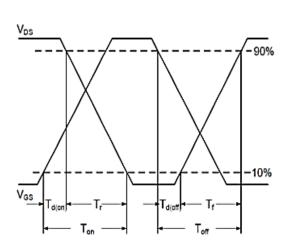


Figure 9. Normalized Maximum Transient Thermal Impedance





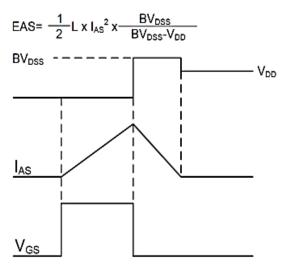
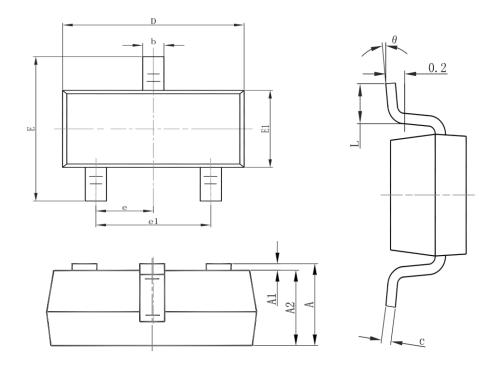


Figure 11. Unclamped Inductive Switching Waveform



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## Package Mechanical Data-SOT23-3-SLS-Single



Gundhal	<b>Dimensions In Millimeters</b>		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
с	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

С



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### **100V N-Channel Enhancement Mode MOSFET**

Edition	Date	Change
Rve1.0	2020/1/31	Initial release

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